Timing Generator for Progressive Scan CCD Image Sensor

Description

The CXD2457R is an IC developed to generate the timing pulses required by Progressive Scan CCD image sensors as well as signal processing circuits.

Features

- Electronic shutter function
- Supports non-interlaced operation
- Base oscillation frequency 30.0MHz
- Horizontal drive frequency switchable between 15/10/5MHz
- Switchable between FINE (Progressive Scan) mode or DRAFT (high-frame rate readout) mode
- Vertical driver

Applications

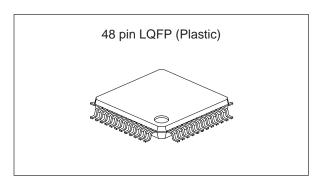
Progressive Scan CCD cameras

Structure

Silicon gate CMOS IC

Applicable CCD Image Sensor

ICX204AK



Absolute Maximum Ratings

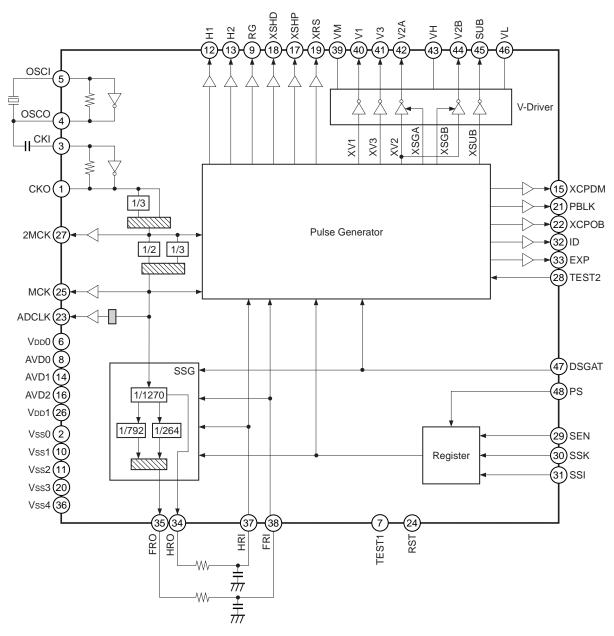
 Supply voltage 	V _{DD} a,	VDDb, VDDC, VDDd	
		Vss - 0.5 to $Vss + 7.0$	V
 Supply voltage 	Vss	VL – 0.5 to VL + 10.0	V
 Supply voltage 	VH	VL - 0.5 to $VL + 26.0$	V
 Supply voltage 	VM	VL - 0.5 to $VL + 26.0$	V
 Input voltage 	Vı	Vss - 0.5 to $Vdd + 0.5$	V
 Output voltage 	Vo	Vss - 0.5 to $Vdd + 0.5$	V
Operating temperating temperations	ature		
	Topr	-20 to +75	$^{\circ}\!\mathbb{C}$
Storage temperature	ure		
	Tstg	-55 to +150	°C

Recommended Operating Conditions

 Supply voltage 1 	Vdda, \	√ddb, Vddc	
		3.0 to 3.6	V
• Supply voltage 2	VDDd	3.0 to 3.6	V
• Supply voltage 3	VH	14.25 to 15.75	V
 Supply voltage 4 	VL	−9.0 to −5.0	V
Supply voltage 5	VM	0	V
Operating temper	ature		
	Topr	-20 to +75	°C

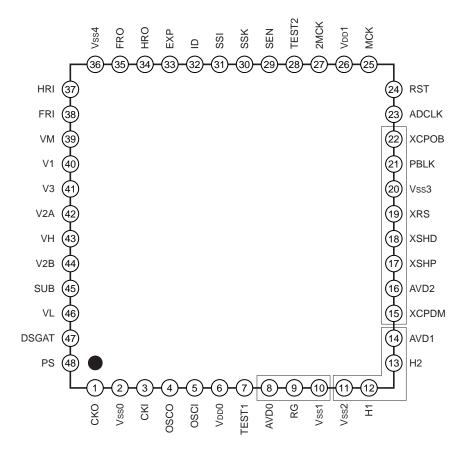
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Block Diagram



XSGA and XSGB are readout pulses that use V2A and V2B, respectively, as the VH value.

Pin Configuration (Top View)



The enclosed pins use separate power supplies.



Pin Description

Pin No.	Symbol	I/O	Description
1	СКО	0	Oscillator output. (30.0MHz)
2	Vss0	_	GND
3	СКІ	I	Oscillator input. (30.0MHz)
4	osco	0	Inverter output for oscillation. (30.0MHz)
5	OSCI	I	Inverter input for oscillation. (30.0MHz)
6	VDD0	_	Power supply.
7	TEST1	I	Test. With pull-down resistor. Fix to low.
8	AVD0	_	Power supply.
9	RG	0	Reset gate pulse output.
10	Vss1	_	GND
11	Vss2	_	GND
12	H1	0	Clock output for horizontal CCD drive.
13	H2	0	Clock output for horizontal CCD drive.
14	AVD1	_	Power supply.
15	XCPDM	0	Clamp pulse.
16	AVD2	_	Power supply.
17	XSHP	0	Sample-and-hold pulse.
18	XSHD	0	Sample-and-hold pulse.
19	XRS	0	Sample-and-hold pulse.
20	Vss3		GND
21	PBLK	0	Blanking cleaning pulse.
22	ХСРОВ	0	Clamp pulse.
23	ADCLK	0	Clock output for AD conversion.
24	RST	I	Reset (Low: Reset, High: Normal operation). Always input one reset pulse during power-on.
25	MCK	0	Clock output for digital circuit.
26	VDD1	_	Power supply.
27	2MCK	0	Clock output for digital circuit.
28	TEST2	I	Test. Fix to high.
29	SEN	I	PS = High: Drive frequency setting input. PS = Low: Serial setting strobe input.
30	SSK	I	PS = High: Readout method setting input. PS = Low: Serial setting clock input.
31	SSI	I	PS = High: Shutter speed setting input. PS = Low: Serial setting data input.
32	ID	0	Line identification signal output write enable pulse output or XSUB output.
33	EXP	0	Pulse output indicating exposure is underway or checksum result output.

Pin	Symbol	I/O	Description
No.	,		·
34	HRO	0	Horizontal sync signal (HR) output or XSGB output.
35	FRO	0	Vertical sync signal (FR) output or XSGA output.
36	Vss4	_	GND
37	HRI	I	Horizontal sync signal (HR) input.
38	FRI	I	Vertical sync signal (FR) input.
39	VM		GND (vertical clock driver GND).
40	V1	0	Clock output for vertical CCD drive.
41	V3	0	Clock output for vertical CCD drive.
42	V2A	0	Clock output for vertical CCD drive.
43	VH	_	15V power supply (vertical clock driver power supply).
44	V2B	0	Clock output for vertical CCD drive.
45	SUB	0	CCD electric charge sweep pulse output.
46	VL	_	-7.5V power supply (vertical clock driver power supply).
47	DSGAT	I	Output stop (Same operation control as SLP when low).
48	PS	ı	Parallel/serial switching for mode setting input method. (High: Parallel, Low: Serial) With pull-down resistor.



Electrical Characteristics

DC Characteristics

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage 1	Vdd0, Vdd1,	VDDa		3.0	3.3	3.6	V
Supply voltage 2	AVD0	VDDb		3.0	3.3	3.6	V
Supply voltage 3	AVD1	VDDC		3.0	3.3	3.6	V
Supply voltage 4	AVD2	VDDd		3.0	3.3	3.6	V
Supply voltage 5	VH	VH		14.5	15.5	15.5	V
Supply voltage 6	VM	VM		_	0.0	_	V
Supply voltage 7	VL	VL		-9.0		-5.0	V
Input voltage 1	CIVI	V _{IH1}		0.7Vppa			V
input voltage i	CKI	VIL1				0.3Vpda	V
Input voltage 2	TECTA DO	V _{IH2}		0.7Vpdb			V
Input voltage 2	TEST1, PS	VIL2				0.3VDDa	V
Input voltage 3	RST, TEST2, SEN, SSK, SSI,	Vt + 1		0.8Vppa			V
input voltage 3	HRI, FRI, DSGAT	Vt – 1				0.2VDDa	V
Output voltage 1	CKO, MCK,	Voн1	Feed current where IoH = −10.0mA	VDDa - 0.8			V
Output voltage 1	2MCK	Vol1	Pull-in current where IoL = 7.2mA			0.4	V
Output voltage 2	out voltage 2 RG	VoH2	Feed current where IoH = −3.3mA	VDDb - 0.8			V
Output voltage 2	KG	Vol2	Pull-in current where IoL = 2.4mA			0.4	V
Output voltage 3	H1, H2	Vонз	Feed current where IoH = -22.0mA	VDDC - 0.8			V
Output voltage 3	111,112	Vol3	Pull-in current where IoL = 14.4mA			0.4	V
Output voltage 4	XCPDM, XSHP, XSHD, XRS,	Voн4	Feed current where $loh = -3.3mA$	VDDd - 0.8			V
Output Voltage 4	PBLK, XCPOB	Vol4	Pull-in current where IoL = 2.4mA			0.4	V
Output voltage 5	ID, EXP, HRO,	Voн5	Feed current where IoH = −2.4mA	Vdda – 0.8			V
Output Voltage 3	FRO	Vol5	Pull-in current where IoL = 4.8mA			0.4	V
Output voltage 6	SUB	Vон6	Feed current where IoH = -4.0mA	VH - 0.25			V
Output voltage o	00B	Vol6	Pull-in current where IoL = 5.4mA			VL + 0.25	V
Output voltage 7	V1, V3	Vом7	Feed current where IoH = -5.0mA	VM – 0.25			V
Output voltage 7	V 1, V 3	Vol7	Pull-in current where IoL = 10.0mA			VL + 0.25	V
		Vом101	Feed current where IoH = −7.2mA	VH - 0.25			V
Output voltage 8	V2A, V2B	Vом102	Pull-in current where IoL = 5.0mA			VM + 0.25	V
Output voitage o	V Z A, V Z D	Vol8	Feed current where IoH = -5.0mA	VM – 0.25			V
		Vol8	Pull-in current where IoL = 10.0mA			VL + 0.25	V



Inverter I/O Characteristics for Oscillation

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Logical Vth	OSCI	LVth			VDDa/2		V
	OSCI	ViH		0.7VDDd			V
Input voltage	0301	VIL				0.3VDDa	V
_	osco	Vон	Feed current where Ioн = -6.0mA	VDDa/2			V
Output voltage		Vol	Pull-in current where IoL = 6.0mA			VDDa/2	V
Feedback resistor	OSCI, OSCO	RFB	VIN = VDDd or Vss	500k	2M	5M	Ω
Oscillator frequency	OSCI, OSCO	f		20		50	MHz

Base Oscillation Clock Input Characteristics

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Logical Vth		LVth			VDDa/2		V
Input voltage	CKI	ViH		0.7VDDa			\ \
	CKI	VIL				0.3VDDa	V
Input amplification		Vin	fmax 50MHz sine wave	0.3			Vp-p

^{*1} Input voltage is the input voltage characteristics for direct input from an external source. Input amplification is the input amplification characteristics for input through capacitor.

Switching Characteristics

$$(VH = 15.0V, VM = GND, VL = -8.5V)$$

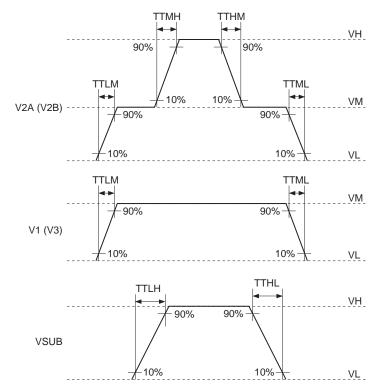
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
	TTLM	VL to VM		350	550	ns
Rise time	TTMH	VM to VH		450	700	ns
	TTLH	VL to VH		50	80	ns
	TTML	VM to VL		250	400	ns
Fall time	TTHM	VH to VM		300	450	ns
	TTHL	VH to VL		50	80	ns
	VCLH				1.0	V
Output noise	VCLL				1.0	V
voltage	VCMH				1.0	V
	VCML				1.0	V

^{*1} The MOS structure of this IC has a low tolerance for static electricity, so full care should be given for measures to prevent electrostatic discharge.

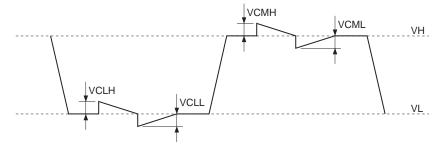
^{*2} For noise and latch-up countermeasures, be sure to connect a bypass capacitor (0.1μF or more) between each power supply pin (VH, VL) and GND.

CXD2457R

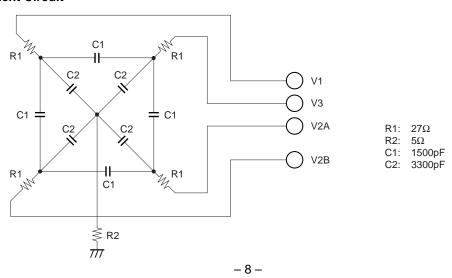
Switching Waveforms



Waveform Noise



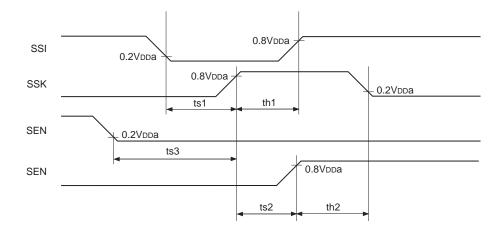
Measurement Circuit





AC Characteristics

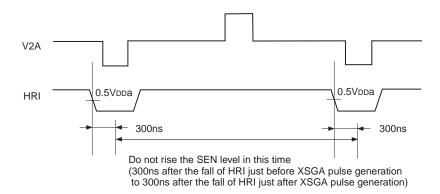
1) AC characteristics between the serial interface clocks



(Within the recommended operating conditions)

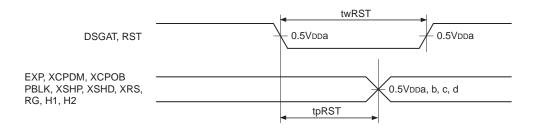
Symbol	Definition	Min.	Тур.	Max.	Unit
ts1	SSI setup time, activated by the rising edge of SSK	20			ns
th1	SSI hold time, activated by the rising edge of SSK	20			ns
ts2	SSK setup time, activated by the rising edge of SEN	20			ns
th2	SSK hold time, activated by the rising edge of SEN	20			ns
ts3	SEN setup time, activated by the rising edge of SSK	20			ns
fk	SSK frequency			7.5	MHz

2) Serial interface clock internal loading characteristics





3) Output timing characteristics using DSGAT and RST



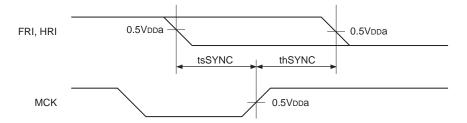
H1 and H2 load capacitance = 180pF

EXP, XCPDM, PBLK, XSHP, XSHD, XRS and RG load capacitance = 10pF

(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tpRST	Time until the above outputs reach the specified value after the fall of DSGAT and RST			75	ns
twRST	RST and DSGAT pulse width	10			ns

4) FRI and HRI loading characteristics



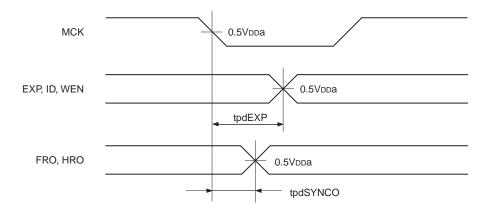
MCK load capacitance = 10pF

(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tsSYNC	FRI and HRI setup time, activated by the rising edge of MCK	5			ns
thSYNC	FRI and HRI hold time, activated by the rising edge of MCK	5			ns



5) Output variation characteristics of ID, WEN, EXP, FRO and HRO



EXP, ID and WEN load capacitance = 10pF

(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tpdEXP	Time until the WEN, ID and EXP outputs change after the fall of MCK	0.5		8.5	ns
tpdSYNCO	Time until the FRO and HRO outputs change after the fall of MCK	1.0		11.5	ns



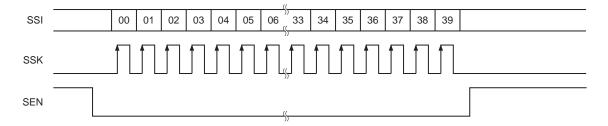
Description of Operation

1. Progressive Scan CCD drive pulse generation

- Combining this IC with a crystal oscillator generates a fundamental frequency of 30.0MHz.
- CCD drive pulse generation is synchronized with HRI and FRI.
- The CCD drive method can be changed to various modes by inputting serial data or parallel data to the CXD2457R.
- The various drive methods possessed by the CXD2457R are shown in the Timing Charts A-1 to 4 (V rate) and B-1 to 6 (H rate).

2. Serial data input method

• All CXD2457R operations can be controlled via the serial interface. The serial data format is as follows.



Serial data format

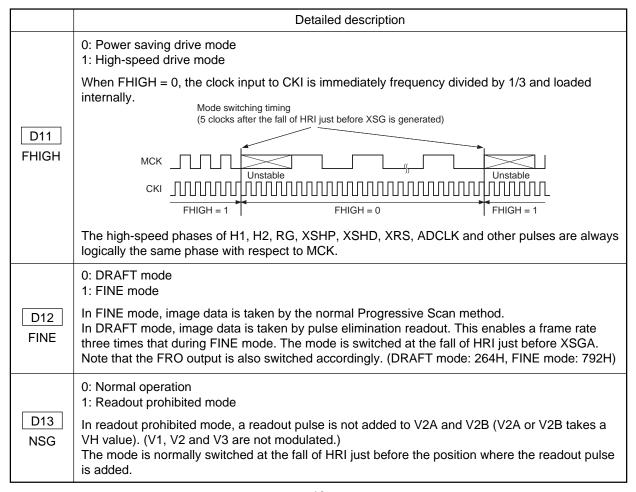
Serial data

Data	Symbol	Function		When reset
D00 to D07	CHIP	Chip switching	See D00 to D07 CHIP.	All 0
D08 to D10	CTGRY	Category switching	See D08 to D10 CTGRY.	All 0
D11 to D31	DATA	Control data for each category The meaning of this CTGRY control data differs according to the category set by D08 to D10.	See D11 to D31 DATA.	All 0
D32 to D39	Checksum bits	Checksum bits	See D32 to D39 CHKSUM.	All 0

3. Serial data and description of functions

	Detailed description												
D00		The serial interface data is loaded to the CXD2457R when D00 and D07 are 1. However, this assumes that D32 to D39 CHKSUM is satisfied.											
to D07	D07	D06	D05	D04	D03	D02	D01	D00	Function				
CHIP								Loading to the CXD2457R					
	This C	This CTGRY data indicates the functions that the serial interface data controls.											
	D10	D09	D08		Function								
D08	0	0	0	Mode	Mode control data								
D10	0	1	0	Elect	ronic s	hutter	contro	l data					
CTGRY	0	1	1	High	-speed	d phase	e adjus	stment	data (Set all of D11 to D31 to 0.)				
	1	0	0	Syste	m sett	ting da	ta						
	Input	Input of values other than those listed above is prohibited.											

CTGRY: Mode control data



NY CXD2457R

	Detailed description										
	0: Normal operation 1: FS mode										
D14 FS	In order to increase the frame rate, a certain portion of the captured image of CCD can be cut out by performing high-speed sweep. In FS mode, high-speed sweep is performed for the V registers of the entire image (period Z) after FRI input. Next, high-speed sweep is performed again for only the desired period (period X) after generating the XSGA pulse. Then, after performing normal V transfer and outputting the effective signal (period Y), high-speed sweep is performed for the entire image again by inputting FRI at the desired timing. This makes it possible to take only the desired portion in the V direction, thus effectively increasing the frame rate. Operation is fixed during period Z, with 22 lines swept every 1H and repeating over a 36H period. During period X, first XSGA is generated, then sweep operation starts. This period is set in serial data FVFS (system setting data: D21 to D26) in HRI units. Be sure to set FINE = 0 in this mode. *When the frame rate is increased as the vertical effective signal Y line (example) Sweep fixed period (period X) Effective signal period (period Z) Timing chart Reset by FRI after normal transfer Reset by FRI after normal transfer Reset by FRI after normal transfer FRI **Timing chart** Reset by FVFS FRI **Timing chart** Reset by FVFS **Timing chart** Reset by FVFS **Timing chart** Reset by FVFS										
D15 to D16	Set to 0.										

to
D18
STB

Detailed description

Operation control settings

The operating mode control bits are loaded to the CXD2457R at the rise timing of the SEN input, and control is applied immediately.

D18	D17	Symbol	Control mode
0	0	CAM	Normal operation mode
0	1	SLP	Sleep mode (mode for the status where CCD drive is not required)
1	Х	STN	Standby mode

Pin status during operation control

1 CKO ACT ACT ACT ACT 25 MCK ACT												
2 Vss0 — — — 26 Vpd1 —<		Symbol	CAM	SLP	STN	RST*		Symbol	CAM	SLP	STN	RST*
3 CKI ACT ACT ACT 27 2MCK ACT ACT	1	СКО	ACT	ACT	ACT	ACT	25	MCK	ACT	ACT	ACT	ACT
4 OSCO ACT ACT ACT ACT 28 TEST2 —	2	Vss0	_	_	_	_	26	VDD1	_	_	_	_
5 OSCI ACT ACT ACT ACT 29 SEN ACT ACT — — 6 VDDO — — — — 30 SSK ACT ACT — — 7 TEST1 — — — — 31 SSI ACT ACT — — 8 AVDO — — — — 32 ID ACT L L L 9 RG ACT L L L 33 EXP ACT L L L 10 Vss1 — — — — 34 HRO ACT ACT L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — —	3	СКІ	ACT	ACT	ACT	ACT	27	2MCK	ACT	ACT	ACT	ACT
6 VDDO — — — — 30 SSK ACT ACT — — 7 TEST1 — — — — 31 SSI ACT ACT — — 8 AVDO — — — — 32 ID ACT L L L 9 RG ACT L L L 33 EXP ACT L L L 10 Vss1 — — — — 34 HRO ACT ACT L L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — — — <	4	osco	ACT	ACT	ACT	ACT	28	TEST2	_	_	_	_
7 TEST1 — — — — 31 SSI ACT ACT — — 8 AVD0 — — — — 32 ID ACT L L L 9 RG ACT L L L 33 EXP ACT L L L 10 Vss1 — — — — 34 HRO ACT ACT L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 —	5	OSCI	ACT	ACT	ACT	ACT	29	SEN	ACT	ACT	_	_
8 AVD0 — — — — 32 ID ACT L L L 9 RG ACT L L L 33 EXP ACT L L L 10 Vss1 — — — — 34 HRO ACT ACT L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — 38 FRI ACT ACT — — 15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT	6	VDD0	_	_	_	_	30	SSK	ACT	ACT	_	_
9 RG ACT L L L 33 EXP ACT L L L 10 Vss1 — — — — 34 HRO ACT ACT L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — 38 FRI ACT ACT — — 15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT VM VM VM 17 XSHP ACT L L L L 42 V2A	7	TEST1	_	_	_	_	31	SSI	ACT	ACT	_	
10 Vss1 — — — 34 HRO ACT ACT L L 11 Vss2 — — — — 35 FRO ACT ACT L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — 38 FRI ACT ACT — — 15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT VM VM VN 17 XSHP ACT L L L 42 V2A ACT VH VH VH	8	AVD0	_	_		_	32	ID	ACT	L	L	L
11 Vss2 — — — — 35 FRO ACT ACT L L L 12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — 38 FRI ACT ACT ACT — 15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT VM VM VM 17 XSHP ACT L L L 41 V3 ACT VM VM VM 18 XSHD ACT L L L 42 V2A ACT VH VH VH	9	RG	ACT	L	L	L	33	EXP	ACT	L	L	L
12 H1 ACT L L L 36 Vss4 — — — — 13 H2 ACT L L L 37 HRI ACT ACT — 14 AVD1 — — — 38 FRI ACT ACT — 15 XCPDM ACT L L L 39 VM — — — 16 AVD2 — — — 40 V1 ACT VM VM VN 17 XSHP ACT L L L 41 V3 ACT VM VM VN 18 XSHD ACT L L L 42 V2A ACT VH VH VH	10	Vss1		_	_	_	34	HRO	ACT	ACT	L	L
13 H2 ACT L L L 37 HRI ACT ACT — — 14 AVD1 — — — — 38 FRI ACT ACT — — 15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT VM VM VN 17 XSHP ACT L L L 41 V3 ACT VM VM VN 18 XSHD ACT L L L 42 V2A ACT VH VH VH	11	Vss2	_	_	_	_	35	FRO	ACT	ACT	L	L
14 AVD1 —	12	H1	ACT	L	L	L	36	Vss4	_	_	_	_
15 XCPDM ACT L L L 39 VM — — — — 16 AVD2 — — — — 40 V1 ACT VM VM VN 17 XSHP ACT L L L 41 V3 ACT VM VM VN 18 XSHD ACT L L L 42 V2A ACT VH VH VH	13	H2	ACT	L	L	L	37	HRI	ACT	ACT	_	_
16 AVD2 — — — 40 V1 ACT VM VM VN 17 XSHP ACT L L L 41 V3 ACT VM VM VN 18 XSHD ACT L L L 42 V2A ACT VH VH VH	14	AVD1	_	_		_	38	FRI	ACT	ACT	_	_
17 XSHP ACT L L L 41 V3 ACT VM VM VM 18 XSHD ACT L L L 42 V2A ACT VH VH VH	15	XCPDM	ACT	L	L	L	39	VM	_	_	_	_
18 XSHD ACT L L 42 V2A ACT VH VH VH	16	AVD2		_	_	_	40	V1	ACT	VM	VM	VM
	17	XSHP	ACT	L	L	L	41	V3	ACT	VM	VM	VM
40 VD0 40T 1 1 40 VII	18	XSHD	ACT	L	L	L	42	V2A	ACT	VH	VH	VH
19 XRS	19	XRS	ACT	L	L	L	43	VH	_	_	_	_
20 Vss3 — — — 44 V2B ACT VH VH VH	20	Vss3	_	_	_	_	44	V2B	ACT	VH	VH	VH
21 PBLK ACT L L L 45 SUB ACT VH VH VH	21	PBLK	ACT	L	L	L	45	SUB	ACT	VH	VH	VH
22 XCPOB ACT L L L 46 VL — — — —	22	ХСРОВ	ACT	L	L	L	46	VL				_
23 ADCLK ACT L L L 47 DSGAT ACT L L	23	ADCLK	ACT	L	L	L	47	DSGAT	ACT	ACT	L	L
24 RST ACT ACT ACT ACT 48 PS ACT ACT ACT AC	24	RST	ACT	ACT	ACT	ACT	48	PS	ACT	ACT	ACT	ACT

^{*} See "6. RST pulse" for a detailed description of RST.

Note) ACT indicates circuit operation, and L indicates "low" output level in the controlled status. For sleep mode or standby mode, stop supplying VH and VL power supplies with CCD image sensor.

	Detailed description											
D19 EXPXEN	 0: The EXP pulse indicating the exposure period is generated. 1: The EXP pulse indicating the exposure period is not generated, and is constantly fixed to low. This bit is invalid when STATUS = 1. Note that the STB setting has priority. The data is reflected at the rise of XSGA. 											
D20 3MCK	O: 2MCK clock system 1: 3MCK clock system This bit switches how MCK is comprised from the clock selected by FHIGH. Note that the waveform is unstable for 5 clocks before and after switching.											
to D23	Invalid data											
D24 to D28	Low-speed electronic shutter setting. The value set here is the number of FR during which readout operation is not performed even if there is input. The setting range is from 0 to 31. When set to 0, readout operation is performed at the first VR. When FS = 1, this bit is invalid.											
VSHUT	MSB LSB Function											
	D28 D27 D26 D25 D24 Number of FR during which readout operation is not performed											
D29 to D31	Invalid data											

CXD2457R clock system

When using a 30MHz crystal

	FHIGH	3MCK	FINE	MCK frequency	2MCK pin output	Frame rate
Mode1	1	0	1	15MHz	30MHz	15Frame/s
Mode2	1	1	0	10MHz	15MHz	30Frame/s
Mode3	0	0	0	5MHz	10MHz	15Frame/s
Mode4	1	0	0	15MHz	30MHz	45Frame/s
Mode5	1	1	1	10MHz	15MHz	10Frame/s

Note) Combinations of FHIGH, 3MCK and FINE other than those listed above are prohibited.



CTGRY: Electronic shutter control data

	Detailed description											
D11 to	High-speed e The value set				JB puls	ses fro	m FR t	to the i	next FR.			
D20	MSB LSB Function											
HSHUT	D20 D19	D18 D17	D16	D15	D14	D13	D12	D11	Number of SUB pulses setting			
D21 to D31	Input 0.											

High-speed and low-speed electronic shutter can be used together. Therefore, the exposure time is as follows:

FR cycle \times VSHUT + (fv – HSHUT) \times HR cycle + 745/MCK frequency [Hz] = Exposure time [s] (fv: Number of HR in 1FR)



CTGRY: System setting data

Detailed description										
O: Internal SSG (Sync Signal Generator) functions operate to generate FRO and HRO. 1: Internal SSG functions are stopped, and the FRO and HRO pulses are fixed to low. Note that the STB setting has priority. When the sync signal is input from external CXD2457R, use it at SGXEN = 1.										
0: Normal operation 1: XSGA and XSGB are output from the FRO and HRO pins. Note that the amplitude of the output pulses are Vss to VDDa.										
These bits select the pulse output from the ID pin.										
Γ			D	14						
			0	1						
	D42	0	ID pulse output	WEN pulse output						
	טוט	1	XSUB pulse output	ID pulse output						
>	KSUB:	Inve	ted SUB pulse outpu	it at the amplitude of	Vss to VDDa					
O: VT (readout clock) is added to V2A, V2B and V3 as normal. 1: VT is not added to V2A, V2B and V3. During readout, only the modulation necessary for readout is performed. Note that this setting has priority over mode control data NSG (D13).										
O: Checksum is not performed and the checksum data is invalid. (However, dummy data must be set in the CHKSUM register.) 1: Checksum is performed. This data is reflected even if the checksum results are NG.										
O: The EXP pulse is output from the EXP pin. 1: High is indicated if the checksum results are OK, and low if the results are NG. This pulse is output at the rise of SEN, and reset high at the fall of SEN. This pulse has priority over mode control data EXP.										
Input 0.										
These bits set the h	nigh-sp	eed s	sweep period (unit: H) in FS mode.						
MSB			LSB							
D26 D25 D24	D23	D22	2 D21							
The high-speed swe	eep is	perfo	rmed 22 times every	1H.						
	1: Internal SSG fun Note that the STB suse it at SGXEN = 0: Normal operation 1: XSGA and XSGE Note that the amplit These bits select the 0: VT (readout clock 1: VT is not added to the control of the	1: Internal SSG functions Note that the STB setting use it at SGXEN = 1. 0: Normal operation 1: XSGA and XSGB are of the Note that the amplitude of the set of the puls These bits select the puls 0: VT (readout clock) is act 1: VT is not added to V2A During readout, only the mote that this setting has 0: Checksum is not performed to the checksum is performed to the checksum is performed to the control data Expenses of the control data Expenses of the control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse is output at the over mode control data Expenses of the pulse o	1: Internal SSG functions are so Note that the STB setting has puse it at SGXEN = 1. 0: Normal operation 1: XSGA and XSGB are output Note that the amplitude of the control of the set of	0: Internal SSG (Sync Signal Generator) functions of 1: Internal SSG functions are stopped, and the FRC Note that the STB setting has priority. When the synuse it at SGXEN = 1. 0: Normal operation 1: XSGA and XSGB are output from the FRO and Hote that the amplitude of the output pulses are Vss. These bits select the pulse output from the ID pin. Diagram of ID pulse output XSUB: Inverted SUB pulse output XSUB: Inverted SUB pulse output XSUB: Inverted SUB pulse output IV XSUB pulse output IV XSUB: Inverted SUB pulse output IV XSUB pulse output IV XS	O: Internal SSG (Sync Signal Generator) functions operate to generate I 1: Internal SSG functions are stopped, and the FRO and HRO pulses at Note that the STB setting has priority. When the sync signal is input fror use it at SGXEN = 1. O: Normal operation 1: XSGA and XSGB are output from the FRO and HRO pins. Note that the amplitude of the output pulses are Vss to Vdda. These bits select the pulse output from the ID pin. D14 O 1 D13 O ID pulse output WEN pulse output XSUB: Inverted SUB pulse output at the amplitude of O: VT (readout clock) is added to V2A, V2B and V3. During readout, only the modulation necessary for readout is performed. Note that this setting has priority over mode control data NSG (D13). O: Checksum is not performed and the checksum data is invalid. (Howev set in the CHKSUM register.) 1: Checksum is performed. This data is reflected even if the checksum ro.: The EXP pulse is output from the EXP pin. 1: High is indicated if the checksum results are OK, and low if the results This pulse is output at the rise of SEN, and reset high at the fall of SEN. over mode control data EXP. These bits set the high-speed sweep period (unit: H) in FS mode. MSB LSB					

	Detailed description
D27 XVCK	0: Normal operation 1: V1, V2 and V3 are inverted and output as XV1, XV2 and XV3. The amplitude is from VL to VM.
D28 to D31	Invalid data

CHKSUM

		Detailed description											
	These	These are the checksum bits.											
D32 to D39	Data is	not re	flected	I to the	D20 D28 D36	D19 D27 D35 nal regirers if c	If sters o	only whum is N	nen che	→ CHKSUM the checksum results are OK. cksum is OK. OK and the data is reflected to the			

4. Shutter speed setting specifications when PS = H

When PS = H, the CXD2457R can be controlled without inputting serial data by using the SEN, SSK and SSI pins.

Pin			Wh	en L		When H		
SEN	FHIGH (horizontal CCD drive frequency)	Serial reg	isters FHI	GH and	d 3MCK = 0.	_	Serial registers FHIGH = 1 and 3MCK = 0.	
SSK	FINE (readout method)	Serial regi CXD2457	ster FINE = 1 and t R operates in FINE					
SSI	HSHUT, VSHUT (exposure time)		Number o	f SUB	L 249 199 217 68	S = H	H 777 727 745 596	
					Upp		When SSI = H (1/2 When SSI = L (1/6	, i

Other registers hold the value input when PS = L, and assume the status indicated by STB when the RST pulse is input.



5. Reflective position of each data

Each serial data is reflected at the timing shown in the table below. The reflection position is the same when PS = H. When using the low-speed electronic shutter, the data is not reflected at FR where XSGA is not generated (a readout pulse is not added to V2A).

Table 5-1. Serial data reflection timing

Data	Reflection position
Mode control data (STB)	SEN rise
Mode control data (EXPXEN)	XSGA pulse rise
Mode control data (other than STB and EXPXEN)	HRI*1 fall just before XSGA pulse generation
Electronic shutter control data	HRI*2 fall just after XSGA pulse generation
High-speed phase adjustment data	HRI*1 fall just before XSGA pulse generation
System setting data (SGXEN)	SEN rise
System setting data (other than SGXEN)	HRI*1 fall just before XSGA pulse generation

^{*1} For FS mode, 7HRI later from FRI fall

6. RST pulse

Setting Pin 30 to low resets the system. The serial data values after reset are as shown in the "Serial data" table.

Also, some internal circuits stop operating when RST = L. For a description of the pin status when RST = L, see the "Pin status during operation control" table given in the detailed description of STB under "3. Serial data and description of functions".

7. DSGAT

DSGAT is ON when low and the CXD2457R is set to sleep mode as with SLP of STB.

Note that control is applied when either or both of DSGAT and SLP are ON. Also, when STN is ON, the CXD2457R is set to standby mode regardless of the DSGAT status.

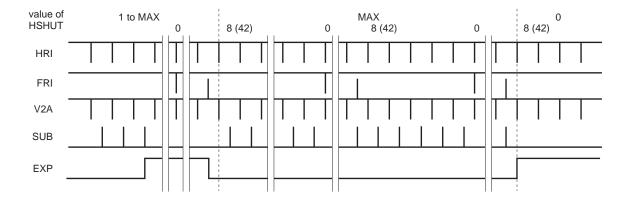
8. EXP pulse

The EXP pulse indicates the exposure period.

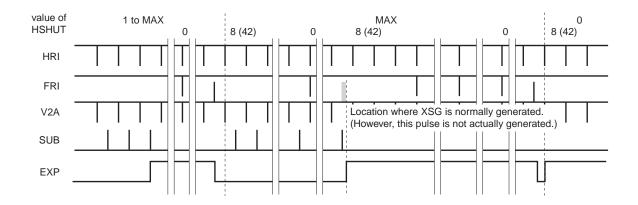
The details are shown on the following pages.

^{*2} For FS mode, 8HRI later from FRI fall

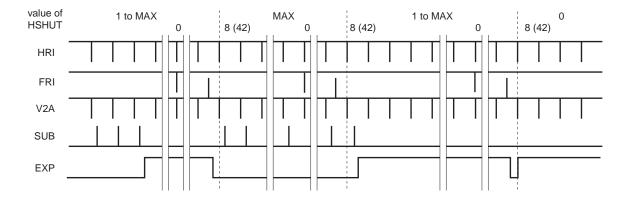
(1) HSHUT ≥ MAX



(2)HSHUT ≥ MAX (with low-speed erectronic shutter)

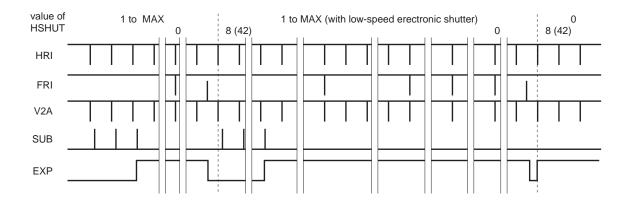


(3) $1 \le HSHUT < MAX$

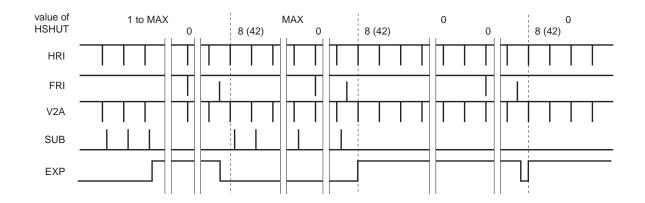


Numbers in parentheses are for FS mode.

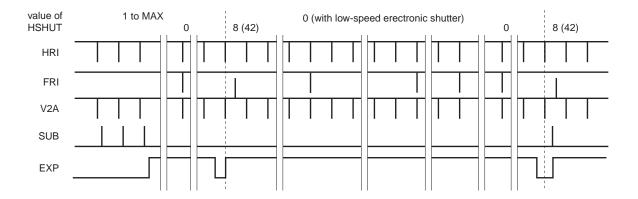
(4) 1 ≤ HSHUT < MAX (with low-speed erectronic shutter)



(5) HSHUT = 0

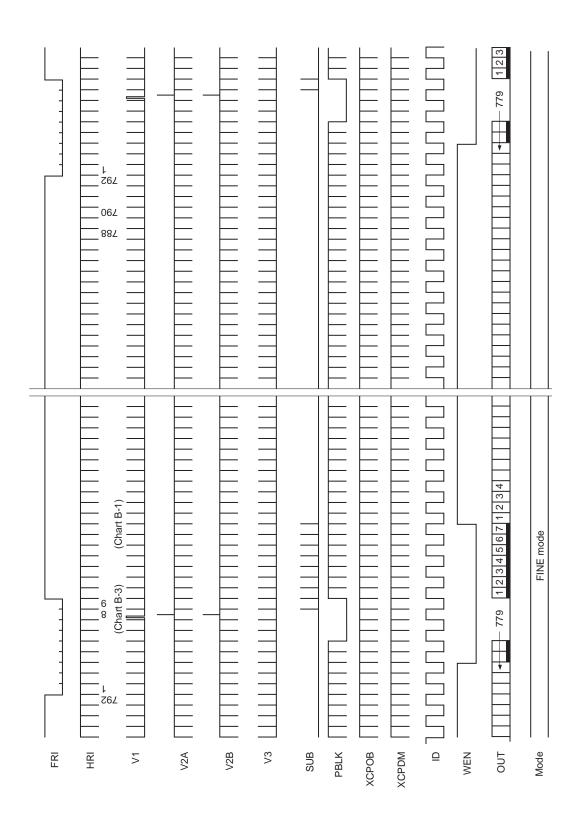


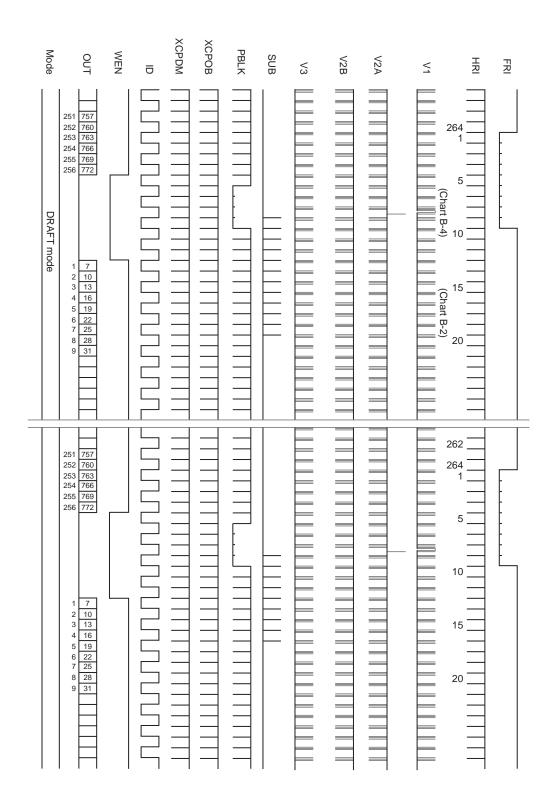
(6) HSHUT = 0 (with low-speed erecyronic shutter)



Numbers in parentheses are for FS mode.

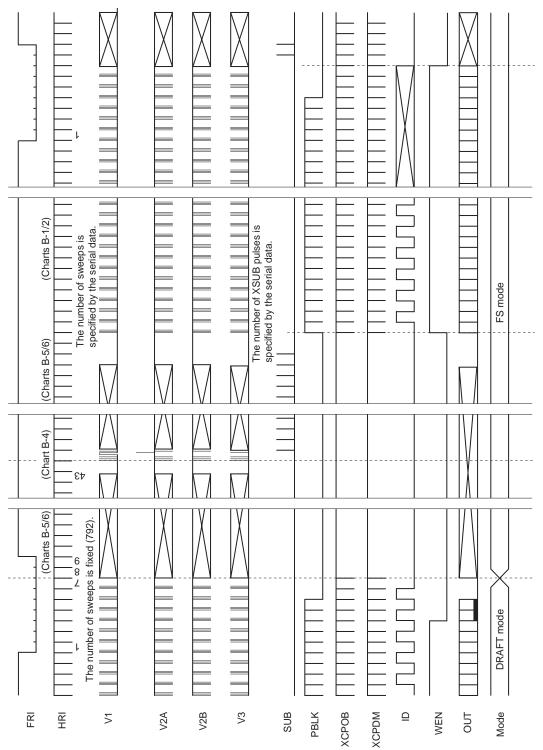
Chart A-1. FINE Mode (Vertical synchronization)





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Chart A-3. FS Mode (Vertical synchronization)



The mode is switched at the point where XSG is normally generated.

Chart A-4. FINE Mode (Vertical synchronization) Low-speed electronic shutter

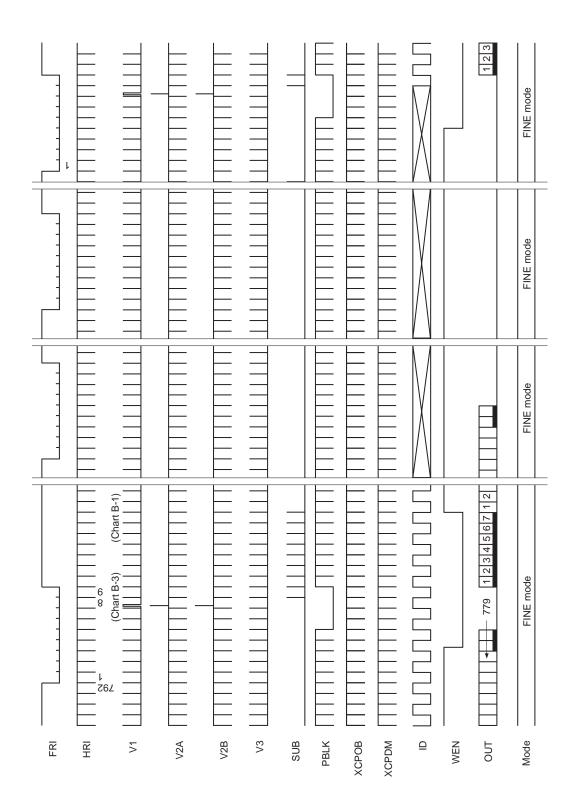
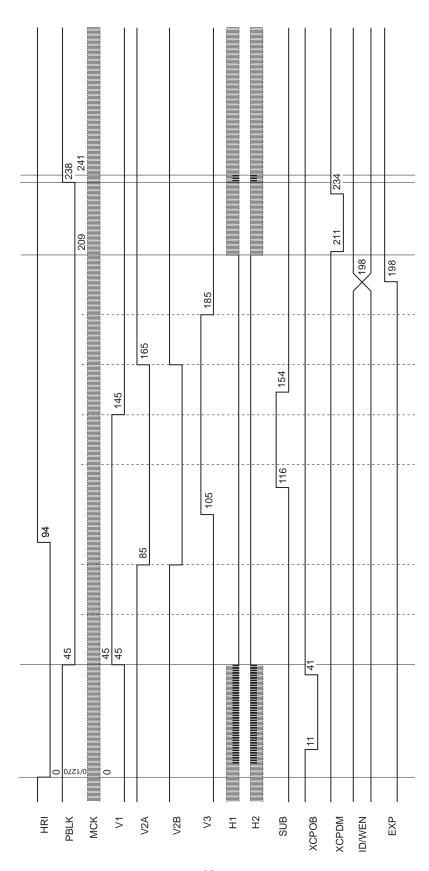
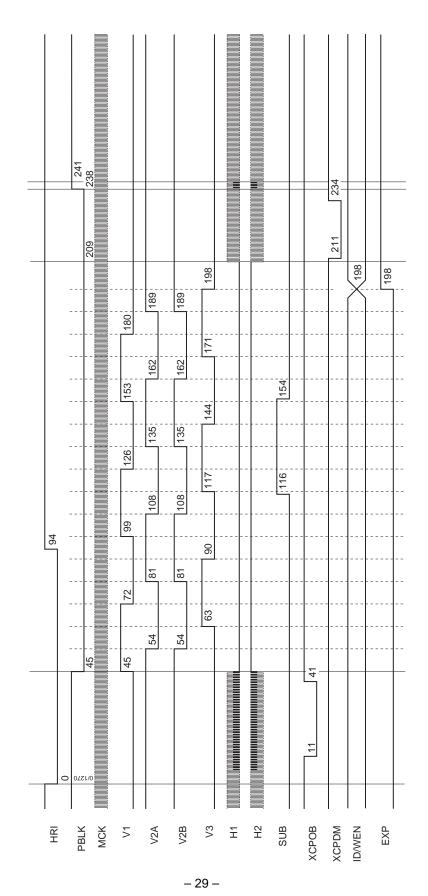
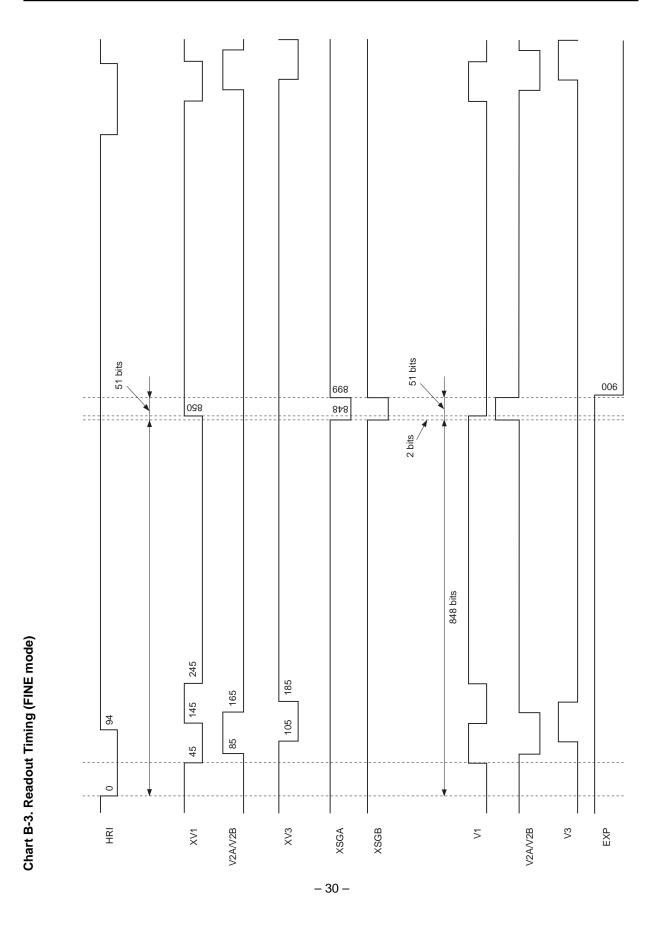


Chart B-1. FINE Mode (Horizontal synchronization)







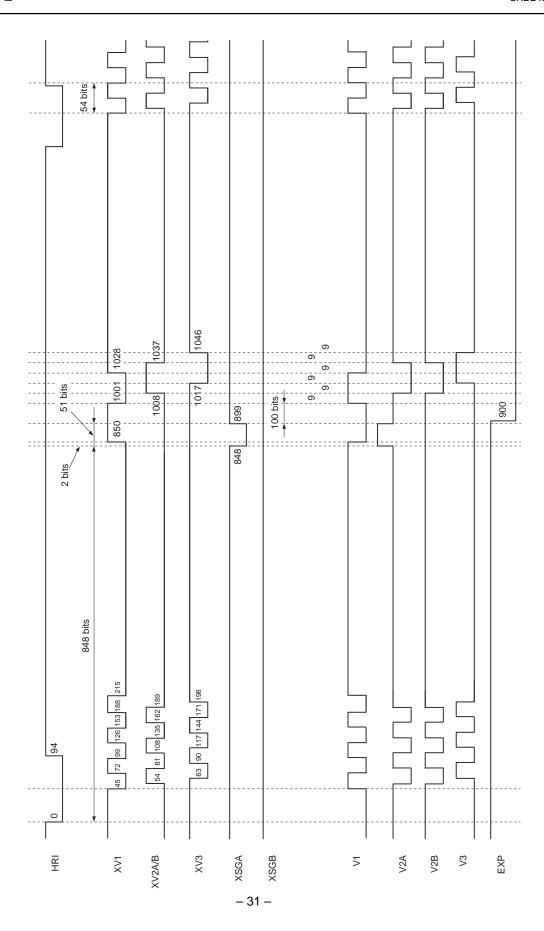
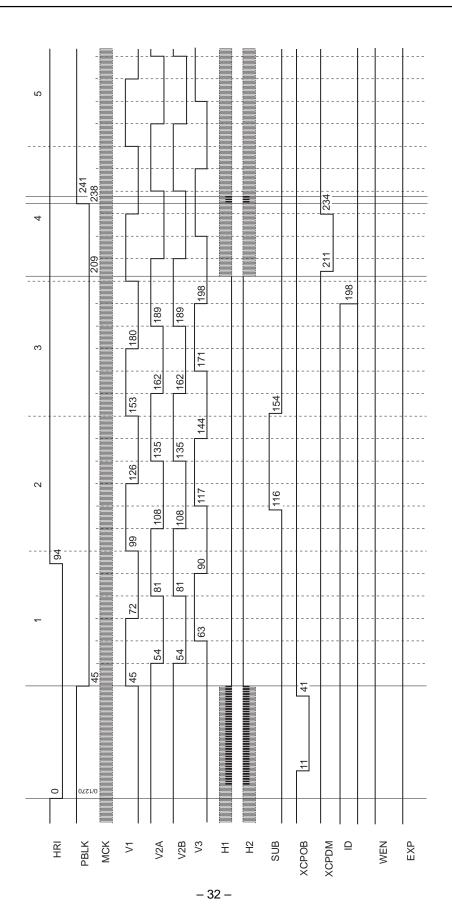
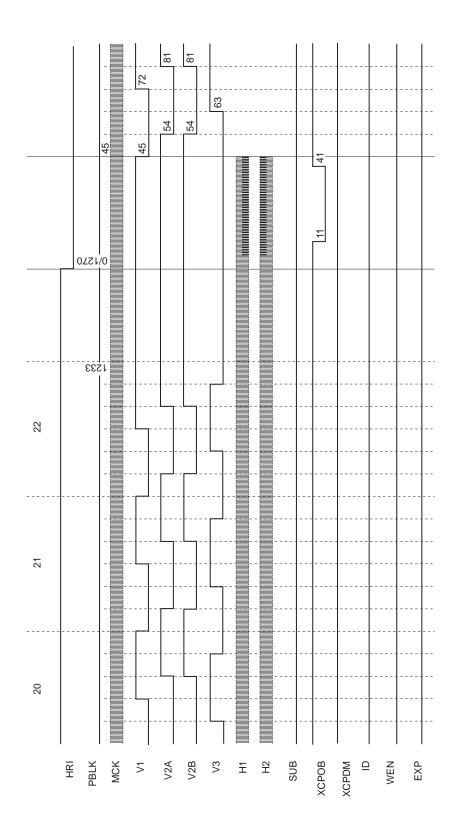
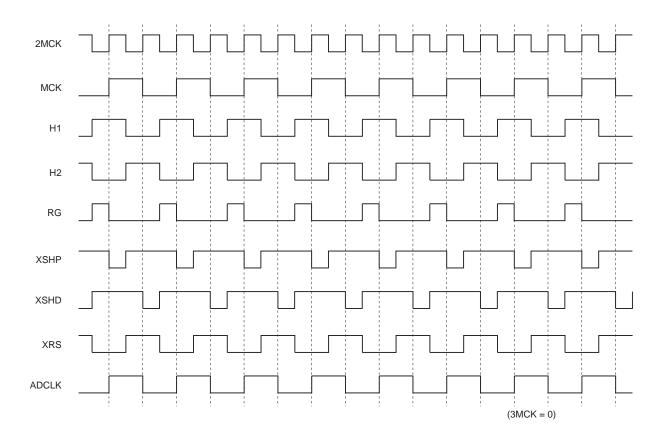


Chart B-5. FS Mode: V clock continuous drive start (Horizontal synchronization)

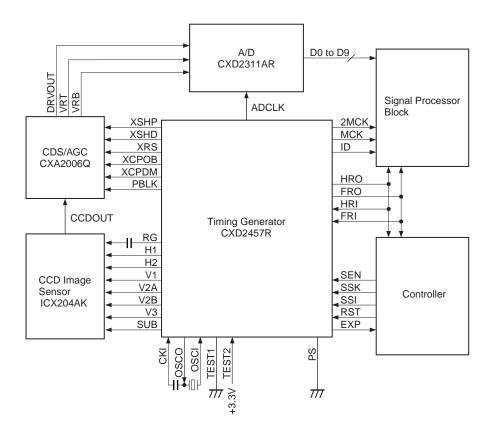




Logical Phase



Application Circuit

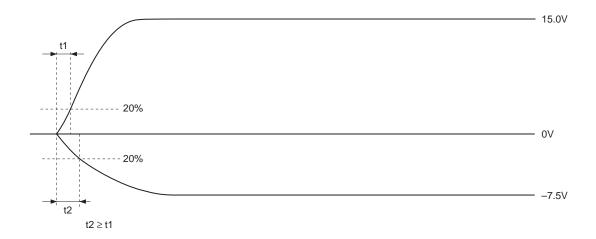


For making FR and HR outside the CXD2457R, configure a circuit that counts MCK. (Using 2MCK, CKO, etc. is not recommended.) Also, set system setting data, SGXEN (D11) to "1" and stop a built-in SSG. Use crystal oscillator (fundamental wave) as base oscillation. Be sure to input duty 50% pulse when crystal oscillator is used.

Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Notes on Turning Power ON

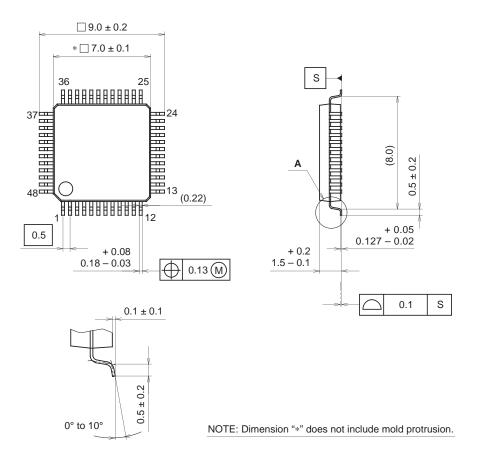
To avoid setting VSUB pin of the CCD image sensor negative potential, the former two power supplies should be raised by the following order among three power supplies, –7.5V, +15.0V and +3.3V.



Package Outline

Unit: mm

48PIN LQFP (PLASTIC)



DETAIL A

SONY CODE	LQFP-48P-L01
EIAJ CODE	LQFP048-P-0707
JEDEC CODE	

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER/PALLADIUM PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.2g